



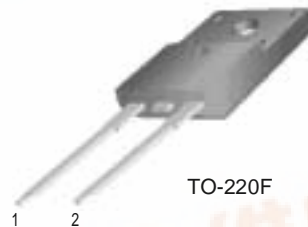
FFPF20U60S

Features

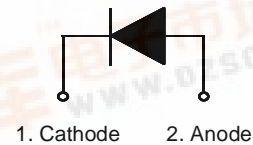
- High voltage and high reliability
- High speed switching
- Low forward voltage

Applications

- General purpose
- Switching mode power supply
- Free-wheeling diode for motor application
- Power switching circuits



TO-220F



ULTRA FAST RECOVERY POWER RECTIFIER

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetitive Reverse Voltage	600	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 100^\circ\text{C}$	20	A
I_{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	120	A
T_J, T_{STG}	Operating Junction and Storage Temperature	- 65 to +150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	1.25	$^\circ\text{C/W}$

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Units
V_{FM}^*	Maximum Instantaneous Forward Voltage $I_F = 20\text{A}$ $I_F = 20\text{A}$ $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$			2.2 2.0	V
I_{RM}^*	Maximum Instantaneous Reverse Current @ rated V_R $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$			10 100	μA
t_{rr} I_{rr} Q_{rr}	Maximum Reverse Recovery Time Maximum Reverse Recovery Current Maximum Reverse Recovery Charge ($I_F = 20\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$)			90 8 360	ns A nC
W_{AVL}	Avalanche Energy	1.0			mJ

* Pulse Test: Pulse Width=300 μs , Duty Cycle=2%

Typical Characteristics

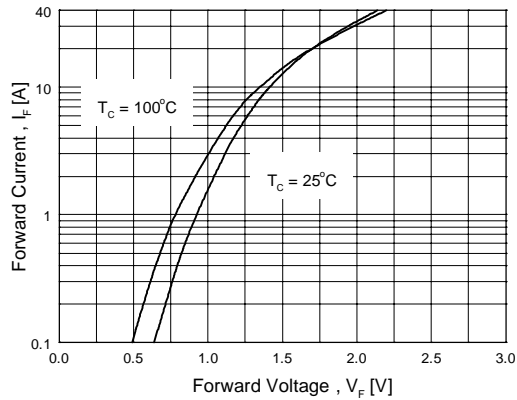


Figure 1. Typical Forward Voltage Drop vs. Forward Current

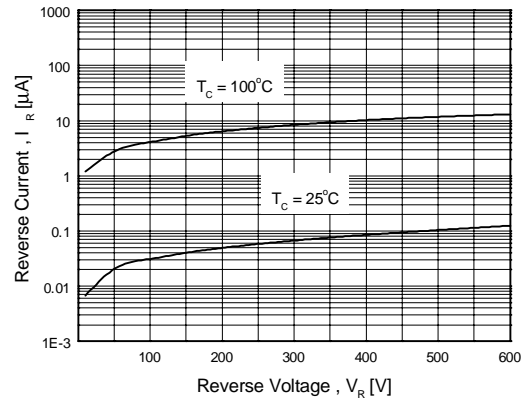


Figure 2. Typical Reverse Current vs. Reverse Voltage

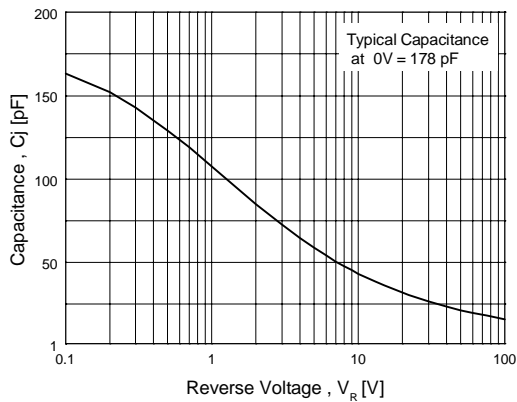


Figure 3. Typical Junction Capacitance

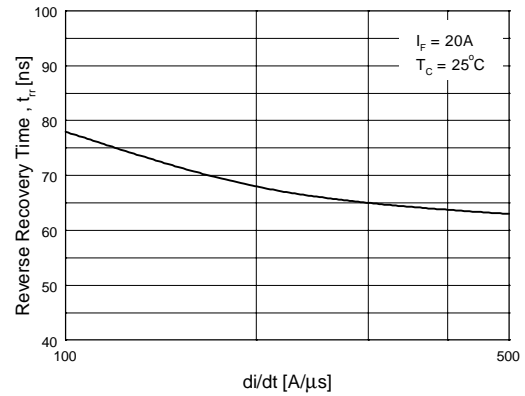


Figure 4. Typical Reverse Recovery Time vs. di/dt

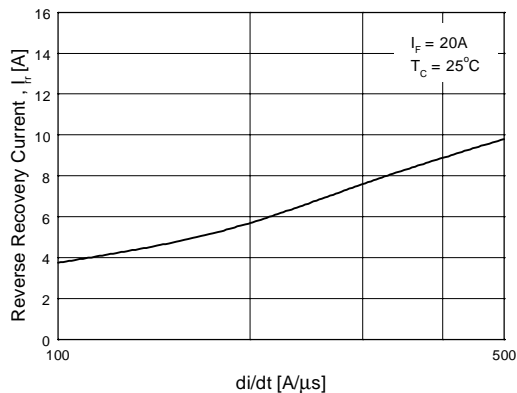


Figure 5. Typical Reverse Recovery Current vs. di/dt

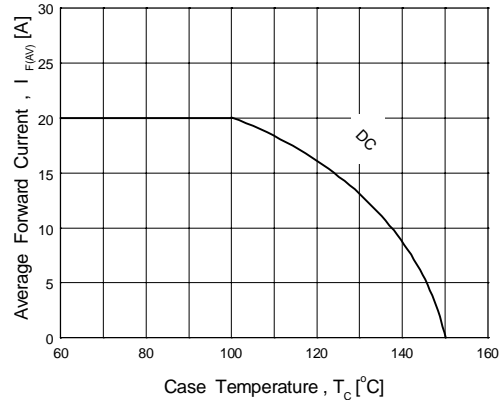


Figure 6. Forward Current Derating Curve

FFPF20U60S

Technical drawing of a 25.4TYP probe, showing three views: front, side, and top views. Dimensions are given in millimeters (mm) with tolerances.

Front View Dimensions:

- Overall width: 10.16 ± 0.20
- Overall height: 15.80 ± 0.20
- Top flange height: 3.30 ± 0.10
- Central hole diameter: $\varnothing 3.18 \pm 0.10$
- Four corner holes (diameter not specified)
- Central hole in lower section (diameter not specified)
- Distance from top flange to lower section: 6.50
- Distance from lower section to base: 9.75 ± 0.30
- Base thickness: $0.50 +0.10/-0.05$
- Probe tip length: 12.00 ± 0.20
- Probe tip diameter: 0.35 ± 0.10
- Probe tip angle: 1.47° (MAX)
- Probe tip offset: 0.80 ± 0.10
- Probe tip material: 2.54 TYP [2.54 ± 0.20]

Side View Dimensions:

- Overall height: 15.87 ± 0.20
- Top flange height: 6.68 ± 0.20
- Base thickness: $0.50 +0.10/-0.05$
- Probe tip length: 12.00 ± 0.20
- Probe tip diameter: 0.35 ± 0.10
- Probe tip angle: 1.47° (MAX)
- Probe tip offset: 0.80 ± 0.10
- Probe tip material: 2.54 TYP [2.54 ± 0.20]

Top View Dimensions:

- Overall width: 9.40 ± 0.20
- Overall height: 4.70 ± 0.20
- Probe tip length: 12.00 ± 0.20
- Probe tip diameter: 0.35 ± 0.10
- Probe tip angle: 1.47° (MAX)
- Probe tip offset: 0.80 ± 0.10
- Probe tip material: 2.54 TYP [2.54 ± 0.20]

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